

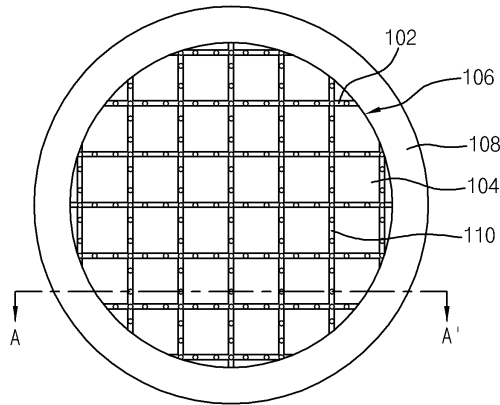
	(19) (12)	(KR) (A)	(11) (43)	10-2010-0039690 2010 04 16
(51) Int. Cl.			(71)	
	<i>HDIL 21/301</i> (2006 01) <i>HDIL 21/78</i> (2006 01)			136-1
(21)	10-2008-0098759		(72)	
(22)	2008 10 08			1008-18 203
			(74)	
	: 6			

(54)

(57)

(Scri be)

- 1b



1

(Scribe)

;

;

;

2

1

,

3

1

,

(Hole)

;

4

1

,

(Laser Beam)

(Drilling)

5

1

,

6

5

,

[0001]

(Sawing)

[0002]

(Wfer)

[0003]

[0004]

[0005]

[0006]

Spin

(Particle)

(Blade

[0007]

(Chipping)

[0008]

[0009]

[0010]

[0011]

[0012]

[0013]

[0014]

(Scribe)

[0015]

[0016]

(Hole)

[0017]

(Drilling)

(Laser Beam)

[0018]

[0019]

[0020] (Scribe) (Step)

[0021]

[0022]

[0023]

[0024]

[0025]

[0026] 1a 1c  
2a 2c 1a 1c A A'

[0027] 1a 2a (Scribe) (102) (104)  
(106) (106) (108)

[0028] (108) WBL (Wafer Backside Lamination) UV (Ultra Violet)  
(108) (106) (104)

[0029] 1b 2b (106) (102) (110)  
(110) (Hole) (Laser Beam) (Drilling)

[0030] (110) (104) (104)  
(104) (106) (106)

[0031] 1c 2c (110) (102) (102)  
(110) (106) (104) (106)

[0032] (112) (112)  
(106) (102) (102) (112)

[0033] (104) (106) (106) (106)  
(110) (106) (106)

[0034] (112) (106) (102) (106)  
(Crack)

(Scribe)

[0035]

(Step)

[0036]

[0037]

[0038]

[0039]

[0040]

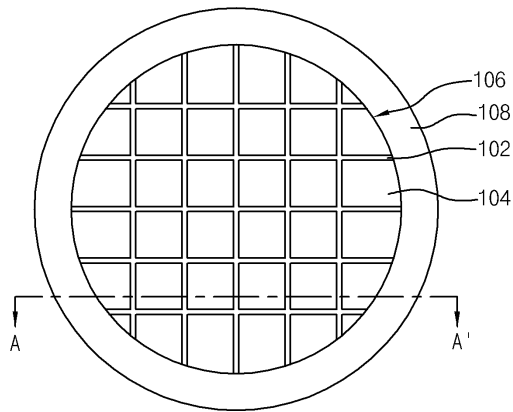
[0041]

1a 1c

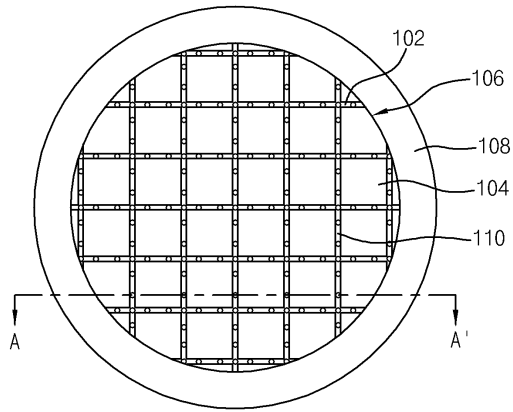
[0042]

2a 2c 1a 1c A-A

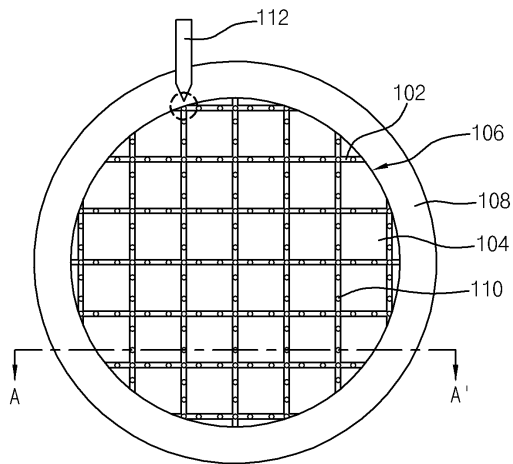
*1a*



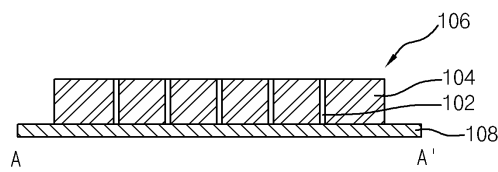
1b



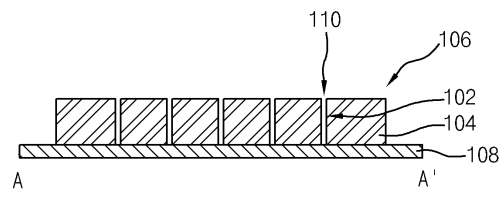
1c



2a



2b



2c

